



U.S. Patent No. 6,475,962B1 6610635 & 6,900,163B2

**MICRO-FAZE<sup>®</sup> A**  
**Dry-to-touch Thermal Pad**  
**Product Code: 52046**

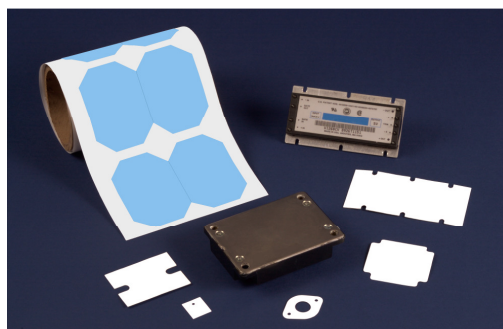


**TECHNICAL DATA SHEET**

**THERMALLY CONDUCTIVE INTERFACE MATERIAL**

**Product Description**

MICRO-FAZE<sup>®</sup> A is a dry-to-touch thermal interface pad formulated with **non-silicone thermal grease**. It was developed by AOS to offer the **low thermal resistance** in a thermal interface without the mess of grease. MICRO-FAZE A is a die-cut **aluminum foil substrate** coated on both sides with specially formulated thermal grease that is naturally tacky but dry to the touch. MICRO-FAZE A is **non-wax-based** and offers **low pressure and temperature** heat transfer properties.



**Product Features & Benefits**

- MICRO-FAZE A retains all the unique advantages of thermal grease but in the form of a thermal interface film.
- **Minimum force** (< 15 psi) is required to achieve total interface contact.
- MICRO-FAZE allows for **total “wetting action”** to fill all microscopic surface voids **without changing phase**.
- Unlike phase change materials, **heat transfer starts at 25°C** or lower, making MICRO-FAZE A an excellent choice for cold plate applications.
- Offers maximum heat transfer capability for power components.
- Excellent replacement for phase change materials and silicone pads.
- MICRO-FAZE A is a **“drop-in-place”** product that is easy to use and handle in a manufacturing environment.
- **Naturally tacky** – no adhesive, fiberglass or other non-conductive material is used that may penalize thermal resistance.
- **Thixotropic** nature prevents run out.
- The material will withstand an operating temperature range of up to 200 °C for brief periods.

**Available Configurations**

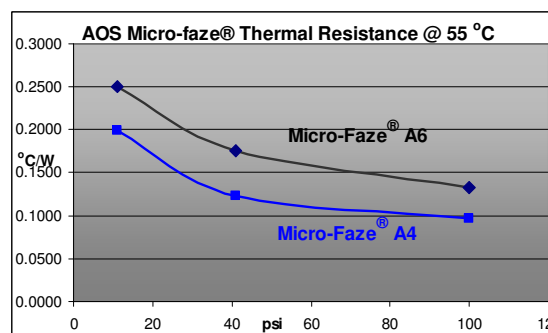
MICRO-FAZE A is available in rolls and can be die-cut to exact specifications.

**Major Applications**

- Power modules, IGBTs, DC-DC converter modules, solid state relays, diodes, power MOSFETs, RF components and thermoelectric modules.
- Microprocessors, multichip modules, ASICs and other digital components.
- Power amplifiers, large area applications for power supplies and other custom enclosure heat dissipating surfaces.

**Typical Properties**

Physical Properties	A4	A6
Substrate	Aluminum	Aluminum
Substrate Thickness	0.002in.	0.002in.
Compound Thickness (per side)	0.001in.	0.002in.
Total Thickness	0.004in.	0.006in.
Thermal Properties		
Thermal Resistance @ 70 psi & 36 °C	0.144 °C-in <sup>2</sup> / W	0.183 °C-in <sup>2</sup> / W
Thermal Conductivity @ 36 °C (ASTM D-5470-06)	3.0 W/m-K	2.8 W/m-K



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